Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Please amend the claims as follows:

1. (Currently Amended) A resin composition for encapsulating a semiconductor chip comprising:

an epoxy resin (A) represented by general formula (1):

$$H_{2}C-CH-CH_{2}-O$$

$$H + CH_{2}-CH_{2}-CH_{2}-CH_{2}$$

$$R$$

$$(1)$$

wherein R represents hydrogen or alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average;

a phenol resin (B) represented by general formula (2):

$$H \xrightarrow{OH} CH_2 - R_1 - CH_2 \xrightarrow{OH} R_2$$
 (2)

wherein R_1 represents phenylene or biphenylene; R_2 represents <u>hydrogen or</u> alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average;

an inorganic filler (C);

a curing accelerator (D);

a silane coupling agent (E); and

Compound (F) containing two and more hydroxyl groups on adjacent carbon atoms in an aromatic ring naphthalene ring.

- 2. (Original) The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the resin composition comprises said Compound (F) in more than or equal to 0.01 wt%.
- 3. (Original) The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the resin composition comprises said silane coupling agent (E) in 0.01 wt% to 1 wt% both inclusive.

4.-5. (Cancelled)

- 6. (Currently Amended) The resin composition for encapsulating a semiconductor chip according to Claim [[5]] 1, wherein said Compound (F) contains two hydroxyl groups on adjacent carbon atoms in said naphthalene ring.
- 7. (Original) The resin composition for encapsulating a semiconductor chip according to Claims 1, wherein the resin composition comprises said inorganic filler (C) in 84 wt% to 90 wt% both inclusive.
- 8. (Previously Presented) A semiconductor device wherein a semiconductor chip is encapsulated by the resin composition according to Claim 1.
- 9. (Previously Presented) The resin composition for encapsulating a semiconductor chip according to Claim 1,

wherein said inorganic filler (C) is present in an amount of 84 wt% to 90 wt% both inclusive,

said silane coupling agent (E) is present in an amount of $\,0.01\,$ wt% to $\,1\,$ wt% both inclusive, and

said Compound (F) is present in an amount of 0.01 wt% to 0.5 wt% both inclusive.